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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Cheng-Lien Chiang
Assignee: Bridge Semiconductor Corporation
Title: OPTOELECTRONIC SEMICONDUCTOR PACKAGE DEVICE
Serial No.: 10/082,500 Filed: February 25, 2002
Examiner: Chu, C. Group Art Unit: 2815
Atty. Docket No.: BDG005-3

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RESPONSE

In response to the Office Action dated December 17, 2002, please amend the application as follows.

In the Specification

Replace the paragraph at page 13, line 28 to page 14, line 2 with the following paragraph:

A1
FIG. 5C is an enlarged plan view of encircled detail 5C in FIG. 5A that shows a representative pad 116 and metal trace 144 in greater detail. Since pad 116 and metal trace 144 are not visible from surface 114 of chip 110, they are shown in phantom. Metal trace 144 includes a distal end that overlaps pad 116.

Replace the paragraph at page 21, lines 8-17 with the following paragraph:

A2
At this stage, device 186 includes chip 110, conductive traces 150, transparent adhesive 154, connection joints 180 and insulative housing 184. Conductive traces 150 each include a lead 138 that protrudes laterally from and extends through a side surface 162 of insulative